SN65HVD62EVM BOM

Drawing Type	BILL OF MATERIALS
Drawing Title	SN65HVD62EVM EVALUATION BOARD
Drawing Number	6559756
Revision	A
ECR number	
Data Class	TI INTERNAL DATA
Engineer	MAHIT WARHADPANDE
Released By	MAHIT WARHADPANDE
Release date	11/15/2012

NOTE: ASTERISK(*) NEXT TO PART MANUFACTURER'S NAME DENOTES POSSIBLE LONG LE

FLYING PROBE TEST PROGRAM DOES NOT EXIST FOR THIS BOARD

ITEM	QTY	MFG	MFG PART#	REF DES	DESCRIPTION	VALUE or FUNCTION
1	4	TAIYO YUDEN / ANY	LMK212BJ106KD-T	C1,C2,C10,C11	CAP,SMT,0805	CAPACITOR,SMT,0805,CERAMIC,10uF,10V,10%,X5R,LOW ESR
2	4	AVX / ANY	0603YC104KAZ2A	C3,C4,C12,C13	CAP,SMT,0603	CAPACITOR,SMT,0603,CERAMIC,0.1uF,16V,10%,X7R
3	2	TDK / ANY	C1608X7R1C105K	C5,C14	CAP,SMT,0603	CAPACITOR,SMT,0603,CERAMIC,1.0uF,16V,10%,X7R
4	2	AVX / ANY	06035A471JAT2A	C6,C15	CAP,SMT,0603	CAPACITOR,SMT,0603,CERAMIC,470pF,50V,5%,C0G(NP0)
5	2	UNINSTALLED	UMK107SD222KA-T(UN)	C7,C16	CAP,SMT,0603	CAPACITOR,SMT,0603,CERAMIC,UNINSTALLED
6	4	AVX / ANY	06035A390JAT2A	C8,C9,C17,C18	CAP,SMT,0603	CAPACITOR,SMT,0603,CERAMIC,39pF,50V,5%,C0G(NP0)
7	12	ANY	wirejumperOPEN	E1,E2,E3,E4,JU1,JU6,JU7,JU12,JU13,JU14,JU15,JU16	JUMPER	2PIN JUMPER
8	2	TI	SN65HVD62	U1,U2	IC,SMT,QFN-16	AISG Modem
9	8	ANY	JUMPER,3P .100cc 123(UN)	JU2,JU3,JU4,JU5,JU8,JU9,JU10,JU11	JUMPER, THRU, 3P	JUMPER,3P .100cc 123
10	2	JOHNSON / EMERSON NETWORK/ANY	142-0701-801	J1,J3	CONNECTOR,SMT	CONNECTOR,SMT,2P,SMA JACK RECEPTACLE, END LAUNCH,062PCB,GOLD
11	2	AMPHENOL/ANY	901-144-8RFX	J2,J4	CONNECTOR,SMA	SMA, FEM, VERT, THREAD
12	2	AVX / ANY		L1,L2	CAP,SMT,0805	CAPACITOR,SMT,0805,CERAMIC,0.22uF,25V,5%,X7R
13	2	VISHAY / ANY	CRCW06031001F	R1,R7	RES,SMT,0603	RESISTOR,SMT,0603,1%,1/10W,1.00K

14	2	VISHAY / ANY	CRCW06034121F	R2,R8	RES,SMT,0603	RESISTOR,SMT,0603,1%,1/10W,4.12K
15	2	YAGEO / ANY	9C06031A1002FKHFT	R3,R9	RES,SMT,0603	RESISTOR,SMT,0603,THICK FILM,10K,1%,1/10W
16	2	PANASONIC / ANY	ERJ-3GSYJ49R9	R4,R10	RES,SMT,0603	RESISTOR,SMT,0603,1%,1/10W,49.9
17	2	VISHAY / ANY	TNPW0603(UN)	R5,R11	RES,SMT,0603	(UNINSTALLED PART)
18	2	PANASONIC / ANY	ERJ-3GSYJ103	R6,R12	RES,SMT,0603	RESISTOR,SMT,0603,5%,1/10W,10K
19	2	COMPONENTS CORP / ANY	TP105-01-04	TP1,TP9	TESTPOINT,THU,1P	TEST POINTS,THU,SMALL,TL-70, YELLOW
20	12	COMPONENTS CORP / ANY	TP105-01-00	TP2,TP4,TP10,TP12,TP19,TP20,TP21,TP22,TP23,TP24,TP25,TP26	TESTPOINT,THU,1P	TEST POINTS,THU,SMALL,TL-70, BLACK
21	12	COMPONENTS CORP / ANY	TP105-01-02	TP3,TP5,TP6,TP7,TP8,TP11,TP13,TP14,TP15,TP16,TP17,TP18	TESTPOINT,THU,1P	TEST POINTS,THU,SMALL,TL-70, RED
22	2	BOURNS	3224W-1-503	VR1,VR2	TRIMPOT,4MM,SMT	TRIMPOT,50K,10%,11T,100ppm,200CY,SEALED
23	2	*HONGKONG CRYSTALS	SSL8704018AEHFF0	Y1,Y2	CRYSTAL,SMT,2P	1500 PIECE MIN 5 WEEK LEAD
24	4	3M	SJ5303		BUMPON HEMISPHERE	BUMPON HEMISPHERE .44X.20 CLEAR
25	20	Tyco	881545-2		SHUNT	SHUNT LP W/HANDLE 2 POS 30AU

Assembly Instructions:

1	Short the following jumpers using the 881545-2 shunts: JU1, JU7, JU15, JU16, JU13, JU14, E1, E2, E3, E4
2	Short positions 1 & 2 of the following 3-pin jumpers using the 881545-2 shunts: JU2, JU8, JU4, JU10, JU5, JU11
3	Short positions 2 & 3 of the following 3-pin jumpers using the 881545-2 shunts: JU3, JU9
4	Install the SJ5303 bumpon hemisphere at the 4 corners of the board on the bottom side.

AD TIME ITEM.

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